(12) INTERNATIONAL APPLICATION PUBLISHED UNDER THE PATENT COOPERATION TREATY (PCT)

(19) World Intellectual Property Organization
International Bureau

(43) International Publication Date
20 June 2002 (20.06.2002)

PCT

(10) International Publication Number
WO 02/049103 A3

(51) International Patent Classification[7]: H01L 23/538, 23/36, 23/498, 21/68, 21/60

(21) International Application Number: PCT/US01/44968

(22) International Filing Date:
15 November 2001 (15.11.2001)

(25) Filing Language: English

(26) Publication Language: English

(30) Priority Data:
09/738,117 15 December 2000 (15.12.2000) US

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(81) Designated States *(national)*: AE, AG, AL, AM, AT, AU, AZ, BA, BB, BG, BR, BY, BZ, CA, CH, CN, CO, CR, CU, CZ, DE, DK, DM, DZ, EC, EE, ES, FI, GB, GD, GE, GH, GM, HR, HU, ID, IL, IN, IS, JP, KE, KG, KP, KR, KZ, LC, LK, LR, LS, LT, LU, LV, MA, MD, MG, MK, MN, MW, MX, MZ, NO, NZ, PH, PL, PT, RO, RU, SD, SE, SG, SI, SK, SL, TJ, TM, TR, TT, TZ, UA, UG, US, UZ, VN, YU, ZA, ZM, ZW.

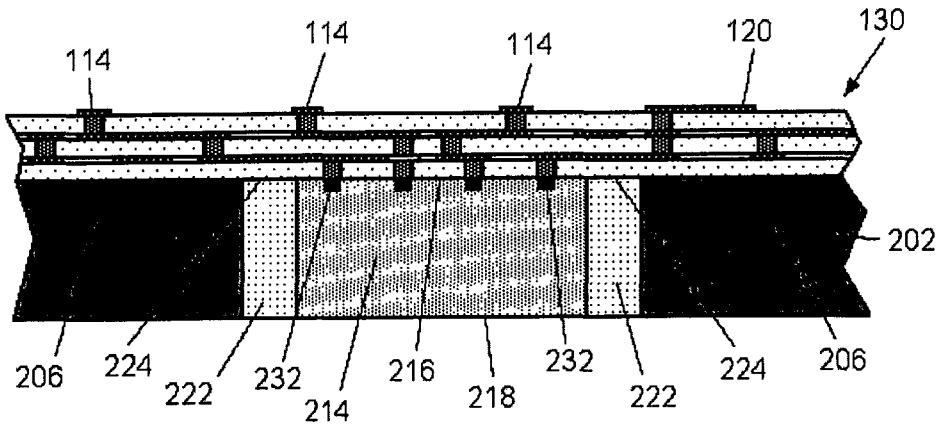
(84) Designated States *(regional)*: ARIPO patent (GH, GM, KE, LS, MW, MZ, SD, SL, SZ, TZ, UG, ZM, ZW), Eurasian patent (AM, AZ, BY, KG, KZ, MD, RU, TJ, TM), European patent (AT, BE, CH, CY, DE, DK, ES, FI, FR, GB, GR, IE, IT, LU, MC, NL, PT, SE, TR), OAPI patent (BF, BJ, CF, CG, CI, CM, GA, GN, GQ, GW, ML, MR, NE, SN, TD, TG).

Published:
— *with international search report*
— *before the expiration of the time limit for amending the claims and to be republished in the event of receipt of amendments*

(88) Date of publication of the international search report:
18 September 2003

For two-letter codes and other abbreviations, refer to the "Guidance Notes on Codes and Abbreviations" appearing at the beginning of each regular issue of the PCT Gazette.

(54) Title: MICROELECTRONIC PACKAGE HAVING BUMPLESS LAMINATED INTERCONNECTION LAYER



(57) Abstract: A microelectronic device fabrication technology that places at least one microelectronic die within at least one opening in a microelectronic package core and secures the microelectronic die/dice within the openings(s) with an encapsulation material, that encapsulates at least one microelectronic die within an encapsulation material without a microelectronic package core, or that secures at least one microelectronic die within at least one opening in a heat spreader. A laminated interconnector of dieelectric materials and conductive traces is then attached to the microelectronic die/dice and at least one of following: the encapsulation material, the microelectronic package core, and the heat spreader, to form a microelectronic device.

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